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DL PACKAGE

SCAS825-JUNE 2006

FEATURES

- Member of the Texas Instruments Widebus™
 Family
- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 4.2 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at V_{CC} = 3.3 V, T_A = 25°C
- I_{off} Supports Partial-Power-Down Mode Operation
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 1000-V Charged-Device Model (C101)

DESCRIPTION/ ORDERING INFORMATION

This 16-bit transparent D-type latch is designed for 1.65-V to 3.6-V $V_{\rm CC}$ operation.

The SN74LVC16373A is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. The device can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

(TOP VIEW) 48 🛭 1LE 10E 47 🛮 1D1 1Q1 2 1Q2 🛮 3 46 🛮 1D2 GND 4 45 GND 1Q3 []5 44 🛮 1D3 1Q4 **[**]6 43 1D4 42 V_{CC} V_{CC} 1Q5 🛮 8 41 🛮 1D5 1Q6 🛮 9 40 1 1D6 GND 10 39 | GND 1Q7 11 38 🛮 1D7 1Q8 📙 12 37 1 1D8 2Q1 **1**3 36 L 2D1 14 35 2Q2 ll 2D2 GND 15 34 🛮 GND 2Q3 16 33 T 2D3 32 🛮 2D4 2Q4 L 17 31 [] V_{CC} V_{CC} **□** 18 2Q5 🛮 19 30 2D5 2Q6 []20 29 2D6 GND 21 28 GND 2Q7 []22 27 2D7 2Q8 [] 23 26 2D8 20Ε Γ 24 25 **∏** 2LE

ORDERING INFORMATION

T _A	PACKAGE ⁽¹)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	SSOP - DL	Tape and reel	CLVC16373AMDLREP	LVC16373AMEP

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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DESCRIPTION/ORDERING INFORMATION (CONTINUED)

 $\overline{\text{OE}}$ does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

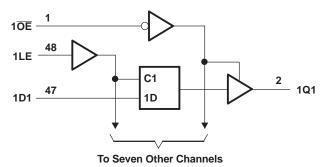
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

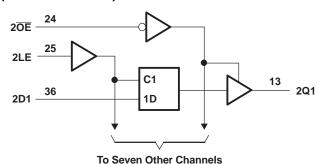
This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

FUNCTION TABLE

ı	NPUTS	3	OUTPUT
ŌΕ	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q_0
Н	Χ	Χ	Z

LOGIC DIAGRAM (POSITIVE LOGIC)







SN74LVC16373A-EP 16-BIT TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	6.5	V
VI	Input voltage range (2)		-0.5	6.5	V
Vo	Voltage range applied to any output in the	e high-impedance or power-off state ⁽²⁾	-0.5	6.5	V
Vo	Voltage range applied to any output in the	e high or low state (2)(3)	-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		- 50	mA
I _{OK}	Output clamp current	V _O < 0		- 50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V _{CC} or 0	GND		±100	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾			63	°C/W
T _{stg}	Storage temperature range ⁽⁵⁾		-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V_{CC} is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.
- (5) Long-term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
1/	Cumply voltage	Operating	1.65	3.6	V
V_{CC}	Supply voltage	Data retention only	1.5		V
	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		
V_{IH}		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
		V _{CC} = 2.7 V to 3.6 V		0.8	
VI	Input voltage		0	5.5	V
\/	Output valtage	High or low state	0	V_{CC}	V
Vo	Output voltage	High-impedance state	0	5.5	V
		V _{CC} = 1.65 V		-4	
	High level output ourrent	$V_{CC} = 2.3 \text{ V}$		-8	mA
I _{OH}	High-level output current	$V_{CC} = 2.7 \text{ V}$		-12	ША
		$V_{CC} = 3 V$		-24	
		V _{CC} = 1.65 V		4	
	Low level output current	$V_{CC} = 2.3 \text{ V}$		8	mΛ
I _{OL}	Low-level output current	$V_{CC} = 2.7 \text{ V}$	12		mA
		$V_{CC} = 3 V$		24	
Δt/Δν	Input transition rise or fall rate			10	ns/V
T _A	Operating free-air temperature		-55	125	°C

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

SN74LVC16373A-EP 16-BIT TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

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Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TEST CONDITIONS		MIN	TYP ⁽¹⁾ MAX	UNIT
	$I_{OH} = -100 \mu A$		1.65 V to 3.6 V	$V_{CC} - 0.2$		
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			
V	$I_{OH} = -8 \text{ mA}$	$I_{OH} = -8 \text{ mA}$				V
V _{OH}	I _{OH} = -12 mA		2.7 V	2.2		V
	1 _{OH} = -12 IIIA		3 V	2.4		
	$I_{OH} = -24 \text{ mA}$	3 V	2.2			
	I _{OL} = 100 μA	1.65 V to 3.6 V		0.2		
	I _{OL} = 4 mA	1.65 V		0.45		
V _{OL}	I _{OL} = 8 mA	2.3 V		0.7	V	
	I _{OL} = 12 mA	2.7 V		0.4		
	I _{OL} = 24 mA		3 V		0.55	
I _I	V _I = 0 to 5.5 V		3.6 V		±5	μΑ
I _{off}	V_I or $V_O = 5.5 \text{ V}$		0		±10	μΑ
I _{OZ}	V _O = 0 to 5.5 V		3.6 V		±10	μΑ
1	V _I = V _{CC} or GND	1 0	3.6 V		20	^
I _{CC}	$3.6 \text{ V} \le \text{V}_1 \le 5.5 \text{ V}^{(2)}$	$I_{O} = 0$	3.0 V	20		μΑ
ΔI_{CC}	One input at V _{CC} – 0.6 V, Other inputs at \	CC or GND	2.7 V to 3.6 V		500	μΑ
C _i	$V_{I} = V_{CC}$ or GND		3.3 V		5	pF
Co	$V_O = V_{CC}$ or GND		3.3 V		6.5	pF

⁽¹⁾ All typical values are at V_{CC} = 3.3 V, T_A = 25°C. (2) This applies in the disabled state only.

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V _{CC} = 2 ± 0.2		V _{CC} = 2	2.7 V	V _{CC} = 3 ± 0.3	3.3 V V	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, LE high	3.3		3.3		3.3		ns
t _{su}	Setup time, data before LE↓	1.7		1.7		1.7		ns
t _h	Hold time, data after LE↓	1.6		1.6		1.6		ns

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTBUT)	V _{CC} = 2 ± 0.2	2.5 V : V	V _{CC} = 2	2.7 V	V _{CC} = 3 ± 0.3	3.3 V V	UNIT
	(INFOT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	
	D	0	1	5.2	1	4.9	1.6	4.2	20
t _{pd}	LE	Q	1	5.2	1	5.3	1.3	4.6	ns
t _{en}	ŌĒ	Q	1	7.7	1	6.2	1.3	5.3	ns
t _{dis}	ŌĒ	Q	1	5.2	1	6.3	2.1	5.9	ns



SN74LVC16373A-EP 16-BIT TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

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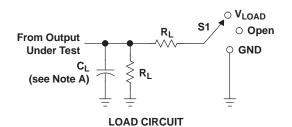
Operating Characteristics

 $T_A = 25^{\circ}C$

PARAMETER			TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT
C	Power dissipation capacitance	Outputs enabled	f = 10 MHz	32	35	39	pF
C_{pd}	per latch	Outputs disabled	1 = 10 NIM2	4	4	6	þΓ

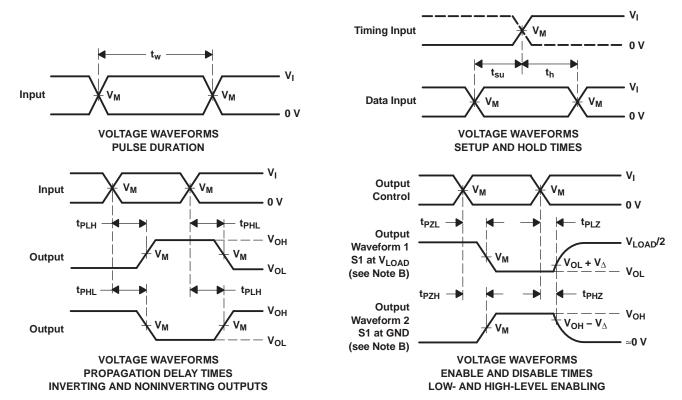


PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

.,	INPUTS		.,	.,		_	.,
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	CL	R _L	V_{Δ}
2.5 V ± 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	50 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins F	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CLVC16373AMDLREP	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/06649-01XE	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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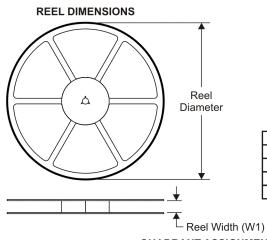
Catalog: SN74LVC16373A

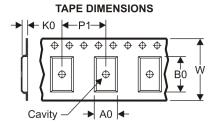
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Catalog - TI's standard catalog product



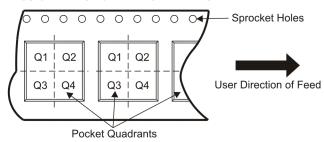
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

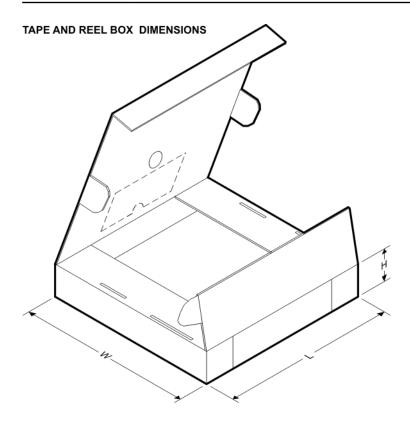
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CLVC16373AMDLREP	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CLVC16373AMDLREP	SSOP	DL	48	1000	346.0	346.0	49.0

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